TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (L^2 - π -MOSV)

2SK2201

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

• Low drain–source ON resistance $: R_{DS} (ON) = 0.28 \Omega (typ.)$ • High forward transfer admittance $: |Y_{fs}| = 3.5 S (typ.)$ • Low leakage current $: I_{DSS} = 100 \mu A (max) (V_{DS} = 100 V)$ • Enhancement–mode $: V_{th} = 0.8 \sim 2.0 V (V_{DS} = 10 V, I_{D} = 1 mA)$

Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	100	V	
Drain-gate voltage (R	_{GS} = 20 kΩ)	V_{DGR}	100	V	
Gate-source voltage		V_{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	3	Α	
	Pulse (Note 1)	I _{DP}	12	Α	
Drain power dissipatio	n (Tc = 25°C)	P_{D}	20	W	
Single pulse avalanche energy (Note 2)		E _{AS}	140	mJ	
Avalanche current		I _{AR}	3	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	2	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	6.25	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	125	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C

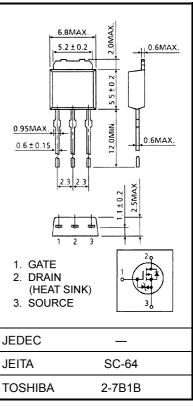
Note 2: V_{DD} = 50 V, T_{ch} = 25°C (initial), L = 25 mH, R_G = 25 Ω , I_{AR} = 3 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

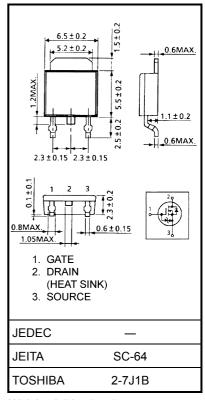
This transistor is an electrostatic sensitive device.

Please handle with caution.

Unit: mm



Weight: 0.36 g (typ.)



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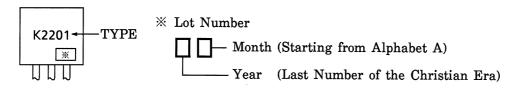
Electrical Characteristics (Ta = 25°C)

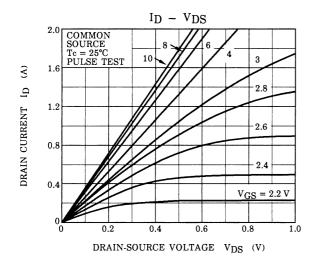
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br voltage	eakdown	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	100	_	_	٧
Gate threshold v	oltage/	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
Drain course ON registers		Pro (OVI)	V _{GS} = 4 V, I _D = 2 A	_	0.36	0.45	Ω
Drain-source ON resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 2 A	_	0.28	0.35		
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2 A	1.5	3.5	_	S
Input capacitano	e	C _{iss}		_	280	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	50	_	pF
Output capacitance		Coss]		105	_	
Switching time	Rise time	t _r	$V_{GS} = \frac{10V}{0V}$ $V_{GS} = \frac{10}{0V}$ $R_{L} = \frac{25\Omega}{25\Omega}$ $V_{DD} = 50V$ $Duty \le 1\%, t_{W} = 10\mu s$	_	20	_	- ns
	Turn-on time	t _{on}		_	50	_	
	Fall time	t _f		_	40	_	
	Turn-off time	t _{off}		_	170	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	13.5	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 80 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		8.5	_	nC
Gate-drain ("miller") charge		Q _{gd}			5	_	

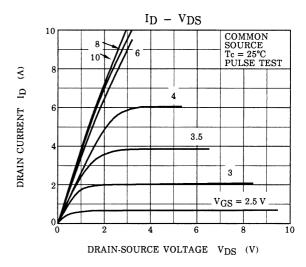
Source-Drain Ratings and Characteristics (Ta = 25°C)

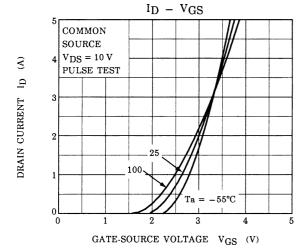
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	3	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	12	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 3 A, V _{GS} = 0 V	_	_	-1.5	V
Reverse recovery time	t _{rr}	$I_{DR} = 3 \text{ A}, V_{GS} = 0 \text{ V}, dI_{DR} / dt = 50 \text{ A} / \mu \text{s}$	_	100	_	ns
Reverse recovery charge	Q _{rr}		_	0.2	_	μC

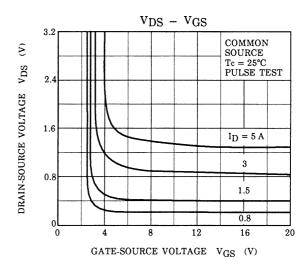
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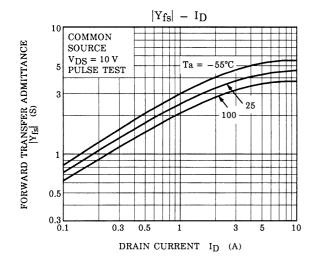


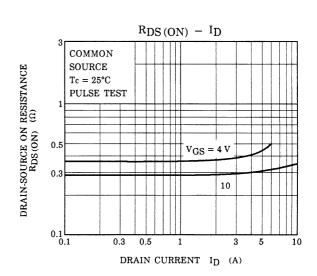




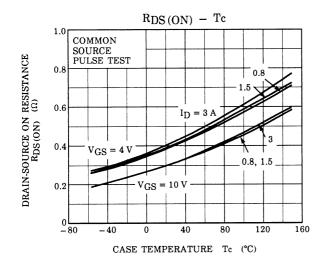


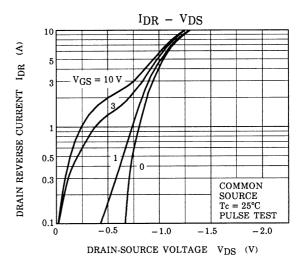


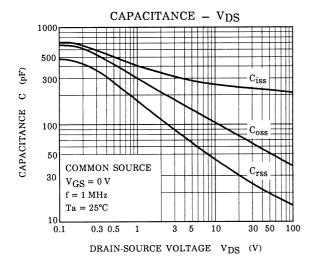


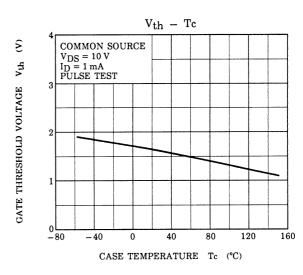


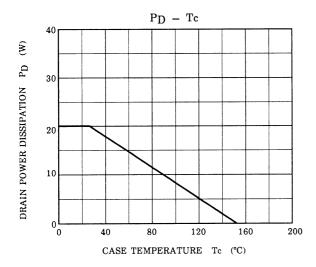
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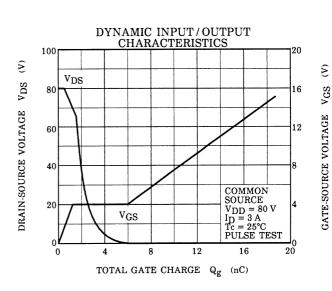




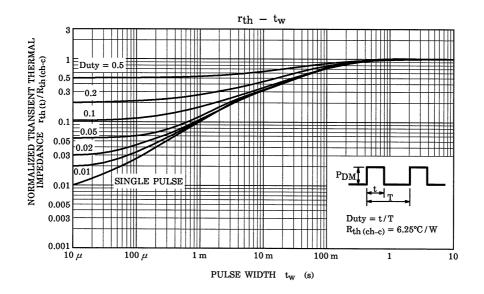


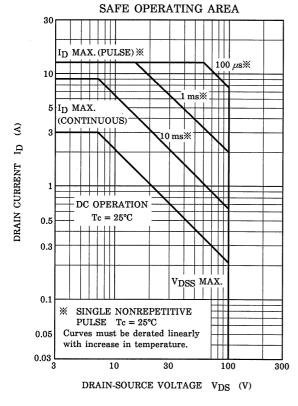


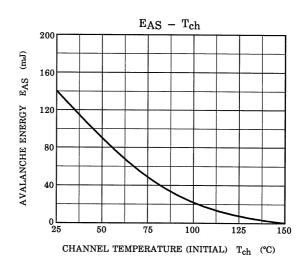


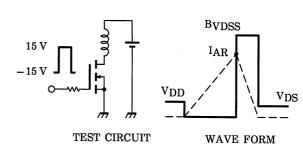


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$$R_G$$
 = 25 Ω
 V_{DD} = 25 V, L = 25 mH

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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